

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT5057457

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|---|--|
| <b>SUBMISSION TYPE:</b>   | NEW ASSIGNMENT                           |
| <b>NATURE OF CONVEYANCE:</b>  | ASSIGNMENT                               |
| <b>CONVEYING PARTY DATA</b>   |  |
| <b>Name</b>   | <b>Execution Date</b>                    |
| RALF OTREMBA  | 09/04/2017                               |
| JOSEF HOEGLAUER   | 09/12/2017                               |
| KLAUS SCHIESS   | 09/04/2017                               |
| XAVER SCHLOEGEL   | 09/13/2017                               |
| AMIRUL AFIQ HUD   | 06/20/2018                               |
| CHOOI MEI CHONG   | 03/08/2018                               |
| LEE SHUANG WANG   | 03/19/2018                               |
| TECK SIM LEE  | 03/08/2018                               |
| MATTHIAS STRASSBURG   | 08/30/2017                               |
| <b>RECEIVING PARTY DATA</b>   |  |
| <b>Name:</b>  | INFINEON TECHNOLOGIES AUSTRIA AG         |
| <b>Street Address:</b>  | SIEMENSSTRASSE 2                         |
| <b>City:</b>  | VILLACH                                  |
| <b>State/Country:</b>   | AUSTRIA                                  |
| <b>Postal Code:</b>   | 9500                                     |
| <b>PROPERTY NUMBERS Total: 1</b>  |  |
| <b>Property Type</b>  | <b>Number</b>                            |
| Application Number:   | 15687682                                 |
| <b>CORRESPONDENCE DATA</b>  |  |
| <b>Fax Number:</b>  |  |
| <i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i> |  |
| <b>Phone:</b>   | 919-948-3390                             |
| <b>Email:</b>   | official@mbhiplaw.com                    |
| <b>Correspondent Name:</b>  | MURPHY, BILAK & HOMILLER/INFINEON TECHNO |
| <b>Address Line 1:</b>  | 1255 CRESCENT GREEN                      |
| <b>Address Line 2:</b>  | SUITE 200                                |
| <b>Address Line 4:</b>  | CARY, NORTH CAROLINA 27518               |
| <b>ATTORNEY DOCKET NUMBER:</b>  | 1012-1980 / 2016P51420 US                |
| <b>NAME OF SUBMITTER:</b>   | MARK R. BILAK, REG. NO. 47,423           |

PATENT

|   |  |
|---|--|
| <b>SIGNATURE:</b>   | /Mark R. Bilak, Reg. No. 47,423/                           |
| <b>DATE SIGNED:</b>   | 07/19/2018   |
|   | This document serves as an Oath/Declaration (37 CFR 1.63). |
| <b>Total Attachments: 12</b><br>source=1012_1980_Declaration#page1.tif<br>source=1012_1980_Declaration#page2.tif<br>source=1012_1980_Declaration#page3.tif<br>source=1012_1980_Declaration#page4.tif<br>source=1012_1980_Declaration#page5.tif<br>source=1012_1980_Declaration#page6.tif<br>source=1012_1980_Declaration#page7.tif<br>source=1012_1980_Declaration#page8.tif<br>source=1012_1980_Declaration#page9.tif<br>source=1012_1980_Declaration#page10.tif<br>source=1012_1980_Declaration#page11.tif<br>source=1012_1980_Declaration#page12.tif |  |

**DECLARATION AND ASSIGNMENT  
FOR PATENT AND DESIGN APPLICATIONS**

UNITED STATES PATENT RIGHTS, OR  
UNITED STATES PLUS ALL FOREIGN PATENT RIGHTS

**A Semiconductor Chip Package Having a Repeating Footprint Pattern**

As a below named inventor (hereinafter designated as the undersigned), I hereby declare that:

This declaration is directed to the application attached hereto. If the application is not attached hereto, the application is as identified by the attorney docket number as set forth above and/or the following:

United States Application Number or PCT International Appln. No. 15/687,682.

filed on August 28, 2017.

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I have reviewed and understand the contents of the above-identified application, including the claims.

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations § 1.56.

WHEREAS, the undersigned has invented certain at least one claim in the application identified.

WHEREAS, Infineon Technologies Austria AG

of Siemensstrasse 2, 9500 Villach, Austria

its heirs, successors, legal representatives and assigns (hereinafter designated as the Assignee) is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent(s) that may be granted therefor in the United States of America and

☒ in any foreign countries.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned has (have) sold, assigned and transferred, and by these considerations does (do) sell, assign and transfer unto said Assignee the full and exclusive right to the said invention in the United States of America, its territories, dependencies and possessions and the entire right, title and interest in and to any and all Letters Patent(s) which may be granted therefor in the United States of America, its territories, dependencies and possessions, and if the box above is designated, in any and all foreign countries; and to any and all divisions, reissues, continuations, conversions and extensions of all of the above for the full term or terms for which the same may be granted.

The undersigned agrees to execute all papers necessary in connection with this application and any continuing, divisional, conversion or reissue applications thereof or any other proceedings before the United States Patent and Trademark Office and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agrees to execute all papers and documents and to perform any act which may be necessary in connection with claims or provisions of the International Convention for the Protection of Industrial Property or similar agreements.



Full Name of Inventor:

**Lee Shuang Wang**

Date

Inventor Signature

Full Name of Inventor:

**Matthias Strassburg**

Date

Inventor Signature

Full Name of Inventor:

**Teck Sim Lee**

Date

Inventor Signature

Full Name of Inventor:

**Xaver Schloegel**

Date

Inventor Signature

*13.09.2017*



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The undersigned hereby authorizes and requests the Patent and Trademark Office Officials in the United States of America and in any foreign countries to issue any and all Letters Patent(s) resulting from said application or any continuing, divisional conversion or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has the full right to convey the entire interest herein assigned, and that he has not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grants the Assignee's legal representatives the power to insert, before or after this document has been executed by the undersigned, any information to identify the instant patent application which may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office.

The undersigned hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

The undersigned hereby acknowledges that any willful false statement made in this declaration is punishable under 18 U.S.C. § 1001 by fine or imprisonment of not more than five (5) years, or both.

In witness whereof, executed by the undersigned on the date opposite the undersigned name.

Full Name of Inventor:

**Ralf Otremba**

\_\_\_\_\_  
Date

\_\_\_\_\_  
Inventor Signature

Full Name of Inventor:

**Amirul Afiq Hud**

\_\_\_\_\_  
20th June 2018

Date

\_\_\_\_\_  
*AMIRUL*

Inventor Signature

Full Name of Inventor:

**Chooi Mei Chong**

\_\_\_\_\_  
Date

\_\_\_\_\_  
Inventor Signature

Full Name of Inventor:

**Josef Hoeglauer**

\_\_\_\_\_  
Date

\_\_\_\_\_  
Inventor Signature

Full Name of Inventor:

**Klaus Schiess**

\_\_\_\_\_  
Date

\_\_\_\_\_  
Inventor Signature

Full Name of Inventor:

**Lee Shuang Wang**

\_\_\_\_\_  
Date

\_\_\_\_\_  
Inventor Signature

Full Name of Inventor:

**Matthias Strassburg**

\_\_\_\_\_  
Date

\_\_\_\_\_  
Inventor Signature

Full Name of Inventor:

**Teck Sim Lee**

\_\_\_\_\_  
Date

\_\_\_\_\_  
Inventor Signature

Full Name of Inventor:

**Xaver Schloegel**

\_\_\_\_\_  
Date

\_\_\_\_\_  
Inventor Signature



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WHEREAS, the undersigned has invented certain at least one claim in the application identified.

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of Siemensstrasse 2, 9500 Villach, Austria

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NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned has (have) sold, assigned and transferred, and by these considerations does (do) sell, assign and transfer unto said Assignee the full and exclusive right to the said invention in the United States of America, its territories, dependencies and possessions and the entire right, title and interest in and to any and all Letters Patent(s) which may be granted therefor in the United States of America, its territories, dependencies and possessions, and if the box above is designated, in any and all foreign countries; and to any and all divisions, reissues, continuations, conversions and extensions of all of the above for the full term or terms for which the same may be granted.

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Full Name of Inventor:

**Ralf Otremba**

\_\_\_\_\_  
Date

\_\_\_\_\_  
Inventor Signature

Full Name of Inventor:

**Amirul Afiq Hud**

\_\_\_\_\_  
Date

\_\_\_\_\_  
Inventor Signature

Full Name of Inventor:

**Chooi Mei Chong**

*CHONG CHOOI MEI*  
\_\_\_\_\_  
Date *8/2/2018*

*[Signature]*  
\_\_\_\_\_  
Inventor Signature

Full Name of Inventor:

**Josef Hoeglauer**

\_\_\_\_\_  
Date

\_\_\_\_\_  
Inventor Signature

Full Name of Inventor:

**Klaus Schiess**


\_\_\_\_\_  
Date

\_\_\_\_\_  
Inventor Signature

Full Name of Inventor:

Wang Lee Shuang  
Date 12/3/2018

**Lee Shuang Wang**

  
Inventor Signature

Full Name of Inventor:

\_\_\_\_\_  
Date \_\_\_\_\_

**Matthias Strassburg**

\_\_\_\_\_  
Inventor Signature

Full Name of Inventor:

8.03.2018  
Date \_\_\_\_\_

**Teck Sim Lee**

  
Inventor Signature

Full Name of Inventor:

\_\_\_\_\_  
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**Xaver Schloegel**

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In witness whereof, executed by the undersigned on the date opposite the undersigned name.

Full Name of Inventor:

**Ralf Otremba**

\_\_\_\_\_  
Date

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Inventor Signature

Full Name of Inventor:

**Amirul Afiq Hud**

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Date

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Inventor Signature

Full Name of Inventor:

**Chooi Mei Chong**

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Date

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Full Name of Inventor:

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Date

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Inventor Signature

Full Name of Inventor:

**Klaus Schiess**

\_\_\_\_\_  
Date

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Inventor Signature

Full Name of Inventor:

**Lee Shuang Wang**

Date

Inventor Signature

Full Name of Inventor:

**Matthias Strassburg**

2017-08-30

Date

  
Inventor Signature

Full Name of Inventor:

**Teck Sim Lee**

Date

Inventor Signature

Full Name of Inventor:

**Xaver Schloegel**

Date

Inventor Signature